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NE-70085US

10/613,069

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July 7, 2003

Not Yet Assigned

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PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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| Oh | T. Takewaki, et al., "Formation of grain-grain copper interconnects by a low-energy ion bombardment process for high-speed ULSIs", <u>Materials Chemistry and Physics</u> 41 (1995) pp. 182-191. |
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DATE CONSIDERED

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